



APPLICATION
FOR
UNITED STATES LETTERS PATENT

Applicant

Kangguo Cheng, et al.

For

"Method and Structure of Vertical
Strained Silicon Devices"

Docket

FIS920030221US1

INTERNATIONAL BUSINESS
MACHINES CORPORATION
ARMONK, NEW YORK 10504

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE
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Signature:

Eric W. Petraske



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE	
<u>In re application of:</u> Kanguo Cheng	<u>Filed:</u> 09/16/2003
	<u>Examiner:</u> K. L. Rose
<u>Serial No.</u> 10/605227	<u>Group Art Unit:</u> 2822
<u>Title:</u> Method and Structure of Vertical Strained Silicon Devices	<u>Docket #:</u> FIS920030221US1

PRELIMINARY AMENDMENT

Commissioner of Patents & Trademarks
Alexandria, VA 22313

Sir:

Please amend the above identified application as follows: